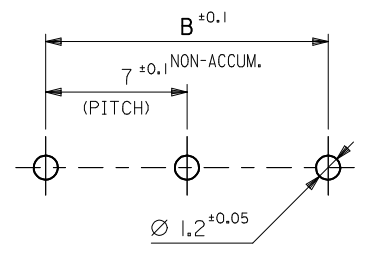
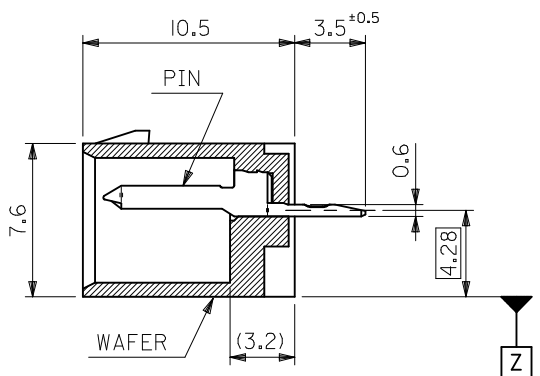
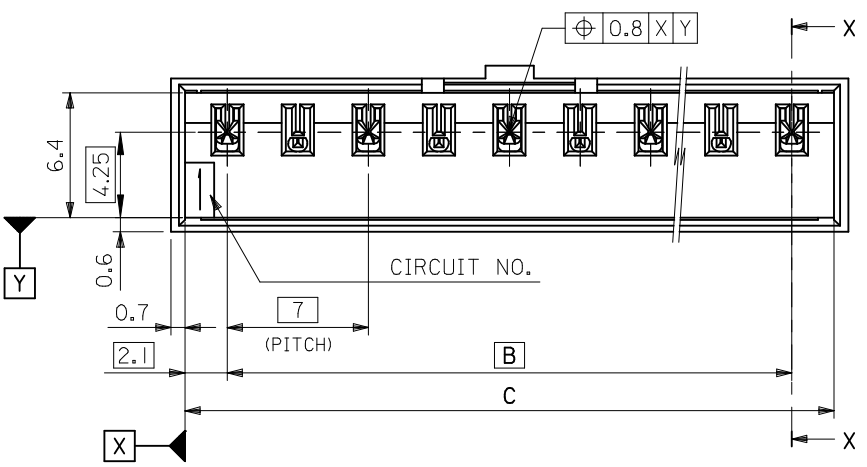
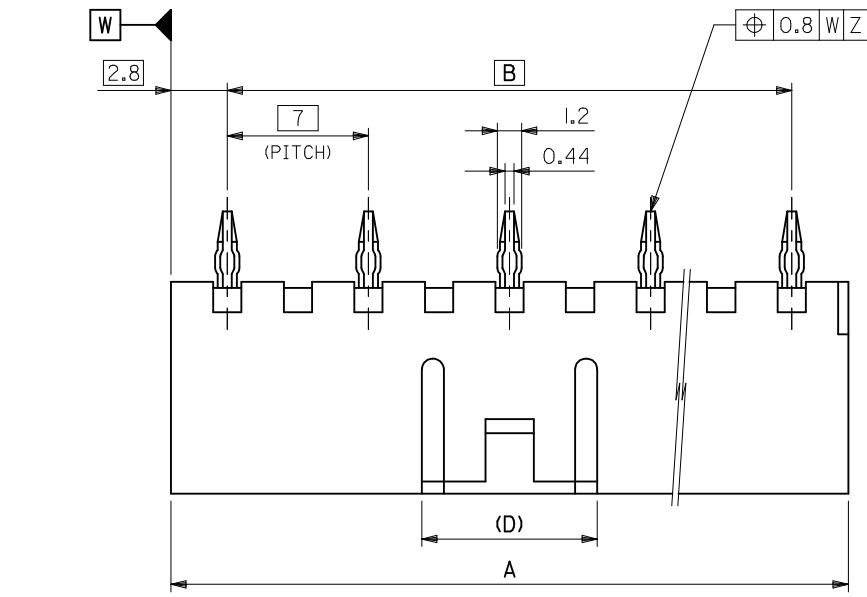


注記 NOTES

1. 嵌合相手：51067 シリーズ
MATE WITH : 51067 SERIES
2. 材質
MATERIAL
ウエハー：PBTP (ガラス15%入り)、UL94V-0
WAFER : PBTP (G.F 15%), UL94V-0
ピン：リン青銅、ニッケル下地 鍍メッキ(+0.254)
PIN : PHOSPHOR BRONZE
TIN OVER NICKEL PLATING (+0.254)
- △ 製品番号の末尾は製品の色を示す。
COLOR OF WAFER
CORRESPONDS TO LAST DIGIT OF MATERIAL NO.
白：WHITE : 53265-***80
黒：BLACK : 53265-***81
赤：RED : 53265-***82
黄：YELLOW : 53265-***83
青：BLUE : 53265-***84
4. 本製品は 53265-***1* の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53265-***1*.



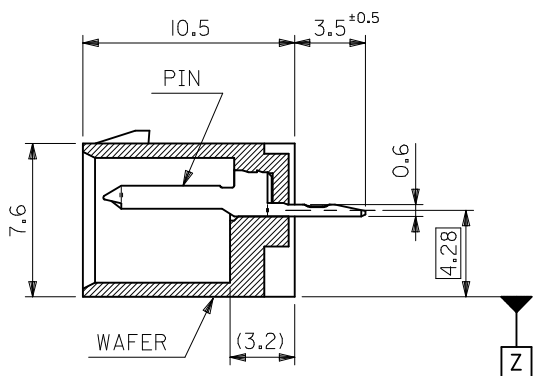
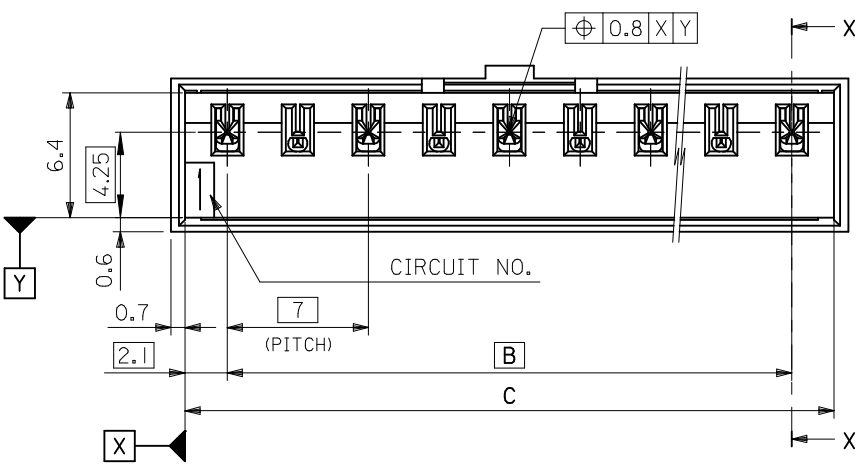
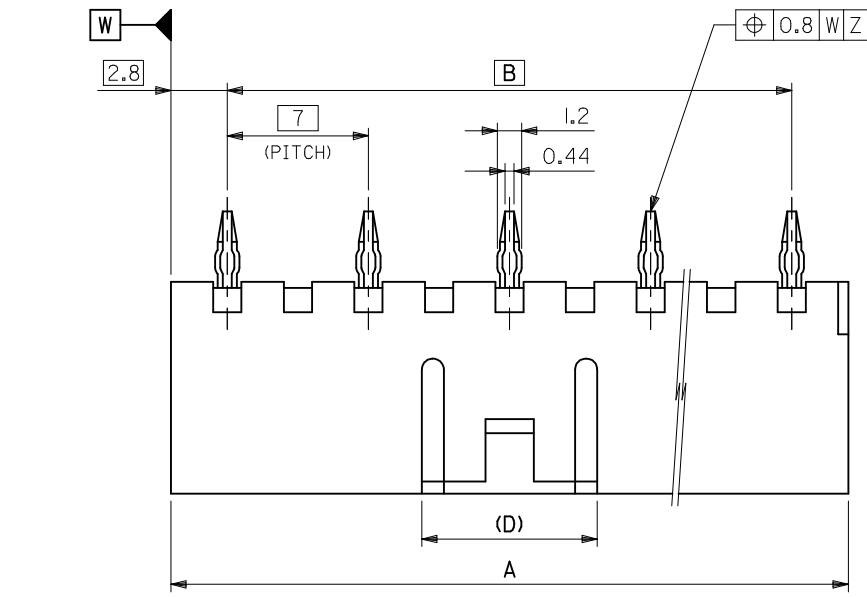
基板取付穴推奨寸法 (参考) (t=1.6)
RECOMMENDED P.C. BOARD HOLE DIM. (REF.)

8.7	53.2	49.0	54.6	53265-088*	8
8.7	18.2	14.0	19.6	53265-038*	3
6.1	11.2	7.0	12.6	53265-028*	2
(D)	C	B	A	TRAY PACKAGE	CKT.
				△ ORDER No. オ-ダ-番号	

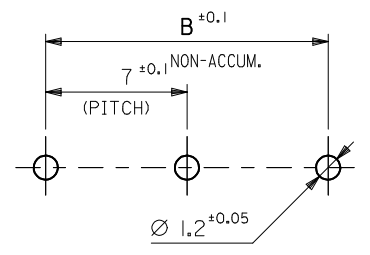
REVISED EC NO: J2017-0224 DRWN: MISHIKAWA 2016/10/12 CHKD: TAKAHASHI 2016/10/12 APPR: MSASAO 2016/10/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	MODEL NO. 53265-***8*
	0.25 UNDER	UNDER	±	DRAWN BY T. UENO	DATE '04/04/13	TITLE 7.0 WIRE TO BOARD CONN. WAFER ASSY ST. -LEAD FREE-	
	0.25 OVER	0.5 UNDER	±	CHECKED BY M. SASAO	DATE '04/04/13		
	0.5 OVER	1.0 UNDER	±	APPROVED BY M. SASAO	DATE '04/04/13		
	0	OVER 10	UNDER	±0.2	MATERIAL NO.		DOCUMENT NO. SD-53265-003
10	OVER 30	UNDER	±0.25	SEE TABLE			
30	OVER		±0.3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
ANGULAR ±3 °			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				

注記 NOTES

1. 嵌合相手：51067 シリーズ
MATE WITH : 51067 SERIES
2. 材質
MATERIAL
ウエハー：PBTP (ガラス15%入り)、UL94V-0
WAFER : PBTP (G.F 15%), UL94V-0
ピン：リン青銅、ニッケル下地 鍍メッキ(+0.254)
PIN : PHOSPHOR BRONZE
TIN OVER NICKEL PLATING (+0.254)
- △ 製品番号の末尾は製品の色を示す。
COLOR OF WAFER
CORRESPONDS TO LAST DIGIT OF MATERIAL NO.
白：WHITE : 53265-***80
黒：BLACK : 53265-***81
赤：RED : 53265-***82
黄：YELLOW : 53265-***83
青：BLUE : 53265-***84
4. 本製品は 53265-***1* の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53265-***1*.



SECT X-X



基板取付穴推奨寸法 (参考) (t=1.6)
RECOMMENDED P.C. BOARD HOLE DIM. (REF.)

8.7	53.2	49.0	54.6	53265-088*	8
8.7	18.2	14.0	19.6	53265-038*	3
6.1	11.2	7.0	12.6	53265-028*	2
(D)	C	B	A	TRAY PACKAGE	CKT.
				△ ORDER No. オ-ダ-番号	

REVISED EC NO: J2017-0224 DRWN: MISHIKAWA 2016/10/12 CHKD: TAKAHASHI 2016/10/12 APPR: MSASAO 2016/10/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	MODEL NO. 53265-***8*
	0.25 UNDER	UNDER	±	DRAWN BY T. UENO	DATE '04/04/13	TITLE 7.0 WIRE TO BOARD CONN. WAFER ASSY ST. -LEAD FREE-	DOCUMENT NO. SD-53265-003
	0.25 OVER	0.5 UNDER	±	CHECKED BY M. SASAO	DATE '04/04/13	SHEET NO. 1 OF 1	
	0.5 OVER	1.0 UNDER	±	APPROVED BY M. SASAO	DATE '04/04/13		
0 OVER	10 UNDER	±0.2	MATERIAL NO.				
10 OVER	30 UNDER	±0.25	SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
30 OVER		±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				
ANGULAR		±3 °					